Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1709-04** DATE: **25-Oct-2017**

Product Affected: VFQFPN-28
(Refer to Attachment II for the affected part numbers)

Date Effective: **25-Jan-2018**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
- ■ Back Mark
- ☐ Date Code
- ☐ Other

Lot # will have:
"RC" prefix for ASECL, Taiwan

Contact: IDT PCN DESK

E-mail: pcndesk@idt.com

Attachment: ■ Yes ☐ No

Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at UTL, Thailand.

There is no change to the moisture performance.

Attachment I details the qualification results.

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

ATTACHMENT I - PCN # : A1709-04

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at UTL, Thailand.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (UTL, Thailand)	**Alternate Assembly (ASECL, Taiwan)**
Die Attach	8600	EN4900G
Bond Wire	Copper Wire	Copper Wire
Mold Compound	G700LTD	G700LA

ATTACHMENT I - PCN # : A1709-04

Qualification Information and Qualification Data:

Affected Packages: VFQFPN-28

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: VFQFPN-36

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
X Ray	IDT Spec. MAC-3012	0/45	0/45	0/45
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	0/25

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test

ATTACHMENT II - PCN # : A1709-04

Part Number	Part Number	Part Number	Part Number
F1451NKGI	F1456NKGI	F1455NKGI8	F1451NKGK
F1456NKGK	F1455NKGK8	F1455NKGI	F1451NKGI8
F1456NKGI8	F1455NKGK	F1451NKGK8	F1456NKGK8